



Semiconductor Device Type: PFA-VQFN-32-5x5x0.9mm-MatteTin						Package Homogeneous Materials				
Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm	24.81	(mg) Total	Mold Compound	% of Total Weight	40.41
Mold Compound	Epoxy Resin	Trade Secret	2.83	1.74	28287		Epoxy Resin	Trade Secret	7.00	
Mold Compound	Phenol Resin	Trade Secret	2.02	1.24	20205		Phenol Resin	Trade Secret	5.00	
Mold Compound	Metal Hydroxide	Trade Secret	0.61	0.37	6061		Metal Hydroxide	Trade Secret	1.50	
Mold Compound	Carbon Black	1333-86-4	0.12	0.07	1212		Carbon Black	1333-86-4	0.30	
Mold Compound	Silica Fused	60676-86-0	34.83	21.39	348329		Silica Fused	60676-86-0	86.20	
Lead Frame	Copper	7440-50-8	51.73	31.76	517307	Total				100.00
Lead Frame	Iron	7439-89-6	1.19	0.73	11905					
Lead Frame	Phosphorus	7723-14-0	0.05	0.03	541	33.22	(mg) Total	Lead Frame	% of Total Weight	54.11
Lead Frame	Zinc	7440-66-6	0.05	0.03	541		Copper	7440-50-8	95.60	
Lead Frame	Silver	7440-22-4	1.08	0.66	10822		Iron	7439-89-6	2.20	
Die Attach	Silver	7440-22-4	0.60	0.37	5963		Phosphorus	7723-14-0	0.10	
Die Attach	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	0.01	0.00	61		Zinc	7440-66-6	0.10	
Die Attach	Dodecyl acrylate	2156-97-0	0.01	0.00	61		Silver	7440-22-4	2.00	
Die Attach	hexamethylene diacrylate	13048-33-4	0.00	0.00	6	Total				100.00
Die	Silicon	7440-21-3	1.65	1.01	16499					
Wire Bond	Copper	7440-50-8	1.61	0.99	16086	0.37	(mg) Total	Die Attach	% of Total Weight	0.61
Wire Bond	Palladium	7440-05-3	0.03	0.02	330		Silver	7440-22-4	97.90	
Wire Bond	Gold	7440-57-5	0.01	0.01	82		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	1.00	
Plating on external leads	Tin	7440-31-5	1.57	0.96	15701		Dodecyl acrylate	2156-97-0	1.00	
TOTALS:			100.00	61.40	1,000,000		hexamethylene diacrylate	13048-33-4	0.10	
61.40 mg Total Mass						Total				100.00
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							Silicon	7440-21-3	100.00	
						Total				100.00
						1.01	(mg) Total	Wire Bond	% of Total Weight	1.65
							Copper	7440-50-8	97.50	
							Palladium	7440-05-3	2.00	
							Gold	7440-57-5	0.50	
						Total				100.00
						0.96	(mg) Total	Plating on external leads	% of Total Weight	1.57
							Tin	7440-31-5	100.00	
						61.40	Total		100.00	100.00